

AMENDMENT

In response to the Office Action dated 25 November
2005. Please amend the above-identified patent application
5 as follows:

In the specifications

(1) Please insert the following sentence at the beginning
of line 14 of page 1: "which is incorporated by reference in
10 its entirety,"

(2) Please amend line 8 of page 45 to read: "the sacrificial
layer. It is ~~totally~~ removed from within"

15 **In the claims**

Please amend the claims as follows:

20 1. (Currently amended)

A method of manufacturing a plurality of micro
enclosures on a substrate wafer, comprising steps of: